

Biren BR100

VENDOR CLAIMED

Biren SPC

OAM

2022

TSMC 7nm

OVERVIEW

256.0

FP32 TFLOPS

64 GB

VRAM HBM2E

1.6 TB/s

Memory Bandwidth

550 W

TDP

PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	2048.0	8	Standard
BF16	1024.0	16	Standard
TF32	512.0	32	Standard
FP32	256.0	32	Standard

MEMORY SPECIFICATIONS

Capacity	64 GB
Type	HBM2E
Bandwidth	1.6 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	550 W
Est. Max Power	633 W
FP32 Efficiency	0.47 TFLOPS/W
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Biren	Architecture: Biren SPC	Process Node: TSMC 7nm
Form Factor: OAM	Launch Year: 2022	

INTERCONNECT

GPU-to-GPU: BLink	Bandwidth: 2.3 TB/s
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